



Material Content Data Sheet



Sales Product Name		BTT6030-2EKB		Issued		9. January 2019		
MA#		MA001854576						
Package		PG-DSO-14-40		Weight*		150.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	2.93	2.93	29330	29330
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		462	
	non noble metal	iron	7439-89-6	1.392	0.92		9248	
	non noble metal	copper	7440-50-8	56.512	37.55	38.53	375525	385351
wire	non noble metal	copper	7440-50-8	1.499	1.00	1.00	9962	9962
encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1099	
	plastics	epoxy resin	-	7.609	5.06		50560	
	inorganic material	silicondioxide	60676-86-0	74.929	49.80	54.97	497909	549568
leadfinish	non noble metal	tin	7440-31-5	1.226	0.81	0.81	8148	8148
plating	noble metal	silver	7440-22-4	1.417	0.94	0.94	9419	9419
glue	plastics	epoxy resin	-	0.217	0.14		1439	
	noble metal	silver	7440-22-4	1.021	0.68	0.82	6783	8222
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com